



Material Content Data Sheet



Sales Product Name		SPA11N60C3		Issued		20. July 2018			
MA#		MA001500114							
Package		PG-TO220-3-317		Weight*		2114.22 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	7.017	0.33	0.33	3319	3319	
leadframe	non noble metal	iron	7439-89-6	1.202	0.06		569		
	inorganic material	phosphorus	7723-14-0	0.361	0.02		171		
	non noble metal	copper	7440-50-8	1200.685	56.79	56.87	567909	568649	
wire	non noble metal	aluminium	7429-90-5	7.867	0.37	0.37	3721	3721	
encapsulation	organic material	carbon black	1333-86-4	8.808	0.42		4166		
	plastics	epoxy resin	-	142.291	6.73		67302		
	inorganic material	silicondioxide	60676-86-0	734.566	34.74	41.89	347440	418908	
leadfinish	non noble metal	tin	7440-31-5	7.889	0.37	0.37	3731	3731	
solder	non noble metal	antimony	7440-36-0	0.354	0.02		167		
	noble metal	silver	7440-22-4	0.884	0.04		418		
	non noble metal	tin	7440-31-5	2.299	0.11	0.17	1087	1672	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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